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## **maXTouch 798-node Touchscreen Controller Product Brief**

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### **Description**

The mXT799T-AT/mXT799T-AB uses a unique charge-transfer acquisition engine to implement Microchip's patented capacitive sensing method. Coupled with a state-of-the-art CPU, the entire touchscreen sensing solution can measure, classify and track a number of individual finger touches with a high degree of accuracy in the shortest response time. The mXT799T-AT/mXT799T-AB allows for both mutual and self capacitance measurements, with the self capacitance measurements being used to augment the mutual capacitance measurements to produce reliable touch information.

### **maXTouch<sup>®</sup> Adaptive Sensing Touchscreen Technology**

- Up to 32 X (transmit) lines and 52 Y (receive) lines
- A maximum of 798 nodes can be allocated to the touchscreen
- Touchscreen size 9.4 inches (16:9 aspect ratio), assuming a sensor electrode pitch of 5.5 mm. Other sizes may be possible with different electrode pitches and appropriate sensor material
- Multiple touch support with up to 16 concurrent touches tracked in real time

### **Automotive Applications**

- AEC-Q100 Qualified
- Developed following Automotive SPICE<sup>®</sup> Level 3 certified processes
- CISPR-25 compliant (for both mutual and self capacitance measurements)

### **Touch Sensor Technology**

- Discrete/out-cell support including glass and PET film-based sensors
- On-cell/touch-on display support including TFT, IPS and OLED
- Synchronization with display refresh timing capability
- Support for standard (for example, Diamond) and proprietary sensor patterns (review of designs by Microchip recommended)

### **Front Panel Material**

- Works with PET or glass, including curved profiles (configuration and stack-up to be approved by Microchip)
- Glass 0.4 mm to 4 mm with GFF stack, 0.55 mm to 4 mm with OGS stack (dependent on screen size, touch size, configuration and stack-up)
- Plastic 0.2 mm to 3 mm (dependent on screen size, touch size, configuration and stack-up)

### **Touch Performance**

- Moisture/Water Compensation
  - No false touch with condensation or water drop up to 22 mm diameter
  - One-finger tracking with condensation or water drop up to 22 mm diameter
- Glove Support
  - Multiple-finger glove touches up to 1.5 mm thickness (subject to stack-up design)
  - Single-finger glove touch up to 5 mm thickness (subject to stack-up design)
- Mutual capacitance and self capacitance measurements supported for robust touch detection
- Noise suppression technology to combat ambient and power-line noise
  - Up to 240 Vpp between 1 Hz and 1 kHz sinusoidal waveform
  - Up to 20 Vpp between 1 kHz and 1 MHz sinusoidal waveform
- Burst Frequency
  - Controlled Tx burst frequency drift over process and temperature range
- Scan Speed
  - Up to 110 Hz one finger reporting rate (subject to configuration)
  - Typical report rate for 10 touches  $\geq 100$  Hz (subject to configuration)
  - Initial touch latency  $< 25$  ms for first touch from idle (subject to configuration)
  - Configurable to allow for power and speed optimization

### **On-chip Gestures**

- Reports one-touch and two-touch gestures

# MXT799T-AT/MXT799T-AB 1.0

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## Keys

- Up to 32 nodes can be allocated as mutual capacitance sensor keys (subject to other configurations)
- Adjacent Key Suppression (AKS) technology is supported for false key touch prevention

## Enhanced Algorithms

- Lens bending algorithms to remove display noise
- Touch suppression algorithms to remove unintentional large touches, such as palm
- Palm Recovery Algorithm for quick restoration to normal state

## Power Saving

- Programmable timeout for automatic transition from active to idle states
- Pipelined analog sensing detection and digital processing to optimize system power efficiency

## Application Interfaces

- I<sup>2</sup>C-compatible slave with support for:
  - Standard mode (up to 100 kHz)
  - Fast mode (up to 400 kHz)
  - Fast-mode Plus (up to 1 MHz)
  - High-speed mode (up to 3.4 MHz)
- SPI slave interface (up to 8 MHz)
- Interrupt to indicate when a message is available
- SPI Debug Interface to read the real-time raw data for tuning and debugging purposes

## Power Supply

- Digital (V<sub>dd</sub>) 3.3 V nominal
- Digital I/O (V<sub>ddIO</sub>) 3.3 V nominal
- Analog (AV<sub>dd</sub>) 3.3 V nominal
- High voltage external X line drive (XV<sub>dd</sub>) up to 9.0 V

## Package

- 144-pin LQFP 20 × 20 × 1.4 mm, 0.5 mm pitch

## Operating Temperature

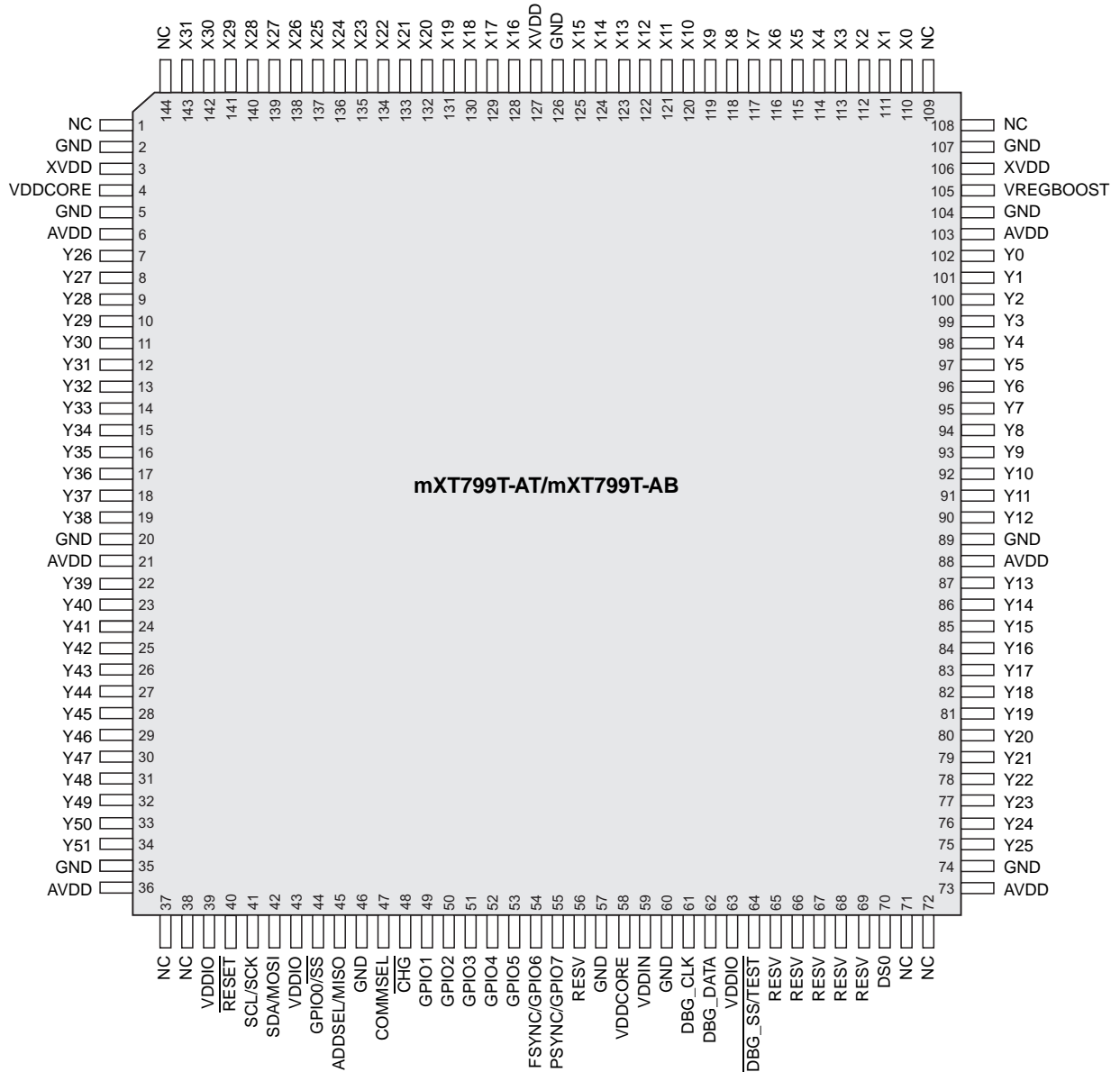
- mXT799T-AT: -40°C to +85°C (Grade 3)
- mXT799T-AB: -40°C to +105°C (Grade 2)

## Design Services

- Review of device configuration, stack-up and sensor patterns
- Custom firmware versions can be considered, such as for specific gestures or proprietary OEM host communication protocols
- Contact your Microchip representative for more information

## PIN CONFIGURATION

### Pin Configuration – 144-pin LQFP



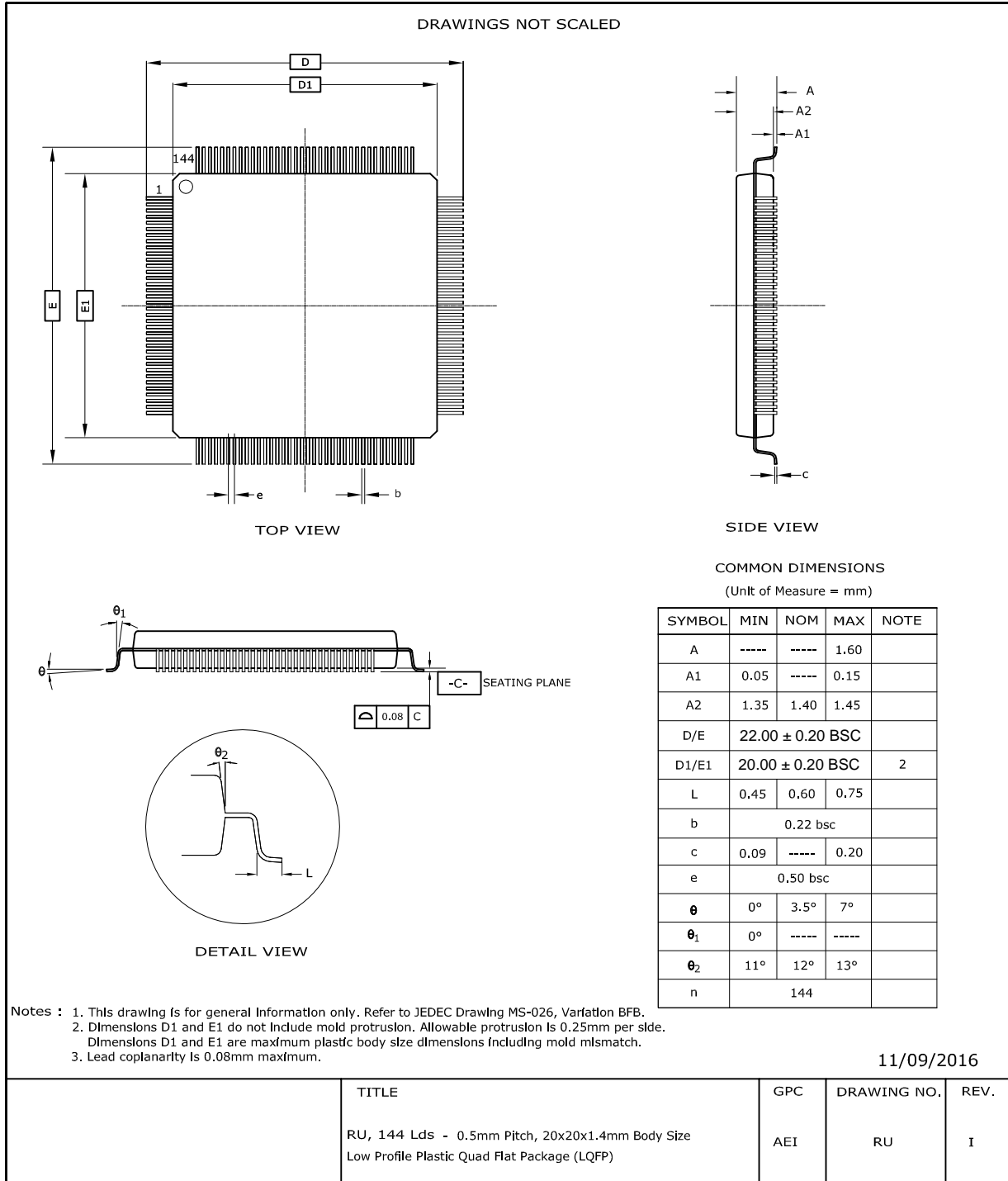
Top view

# MXT799T-AT/MXT799T-AB 1.0

## 1.0 PACKAGING INFORMATION

The following section gives the technical details of the package for the device.

### 1.1 144-pin LQFP 20 x 20 x 1.4 mm



## APPENDIX A: REVISION HISTORY

### Revision A (October 2017)

Initial edition for firmware revision 1.0.AB – Release

# MXT799T-AT/MXT799T-AB 1.0

## PRODUCT IDENTIFICATION SYSTEM

The table below gives details on the product identification system for maXTouch devices. See [“Orderable Part Numbers”](#) below for example part numbers for the mXT799T-AT/mXT799T-AB.

To order or obtain information, for example on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	-XXX	[X]	[XX]	[X]	[XXX]																																																																																																						
Device	Package	Temperature Range	Sample Type	Tape and Reel Option	Pattern																																																																																																						
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<p><b>Note 1:</b> Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. See <a href="#">“Orderable Part Numbers”</a> below or check with your Microchip Sales Office for package availability with the Tape and Reel option.</p>																																																																																																											

## Orderable Part Numbers

Orderable Part Number	Firmware Revision	Description
ATMXT799T-AT (Supplied in trays)	1.0.AB	144-pin LQFP 20 x 20 x 1.4 mm, RoHS compliant Operating temperature range -40°C to +85°C (Grade 3) Automotive grade sample; suitable for automotive characterization
ATMXT799T-ATR (Supplied in tape and reel)		
ATMXT799T-AB (Supplied in trays)	1.0.AB	144-pin LQFP 20 x 20 x 1.4 mm, RoHS compliant Operating temperature range -40°C to +105°C (Grade 2) Automotive grade sample; suitable for automotive characterization
ATMXT799T-ABR (Supplied in tape and reel)		

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